

## ABSTRACT OF THE DISCLOSURE

A semiconductor integrated circuit device which requires high packaging density adopts a method for forming 5 bumps in a terminal section of a semiconductor chip and bonding the semiconductor chip directly on a substrate. In this case, in order to prevent damage to the semiconductor integrated chip, which would otherwise be caused by bonding pressure employed at the time of bonding operation, non-connected dummy 10 bumps are provided at corner sections of the semiconductor chip. Even when the dummy bumps are provided, there arises a necessity for preventing an increase in the size of the semiconductor chips, which would otherwise arise when the dummy bumps are provided on the chip.